

General Description

The AAT8543 is a low threshold MOSFET designed for the battery, cell phone, and PDA markets. Using AnalogicTech™'s ultra high density MOSFET process and space saving small outline J-lead package, performance superior to that normally found in a TSOP-6 footprint has been squeezed into the footprint of a SC70 package.

Features

- $V_{DS(MAX)} = -20V$
- $I_{D(MAX)}^{D(MAX)} = -4.2A @ 25^{\circ}C$
- Low $R_{DS(ON)}$:

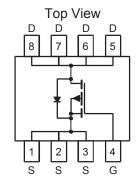
 57 mΩ @ V_{GS} = -4.5V

 104 mΩ @ V_{GS} = -2.5V

SC70JW-8 Package

Applications

- **Battery Packs**
- Cellular & Cordless Telephones
- Battery-powered portable equipment



Absolute Maximum Ratings (T_A=25°C unless otherwise noted)

Symbol	Description		Value	Units	
V _{DS}	Drain-Source Voltage		-20	V	
V _{GS}	Gate-Source Voltage		±12		
I _D	Continuous Drain Current @ T _J =150°C ¹	T _A = 25°C	±4.2	Α	
		T _A = 70°C	±3.3		
I _{DM}	Pulsed Drain Current ²		±20		
I _S	Continuous Source Current (Source-Drain Diode) 1		-1.2		
P _D	Maximum Power Dissipation ¹	T _A = 25°C	1.6	W	
		T _A = 70°C	1.0		
T _J , T _{STG}	Operating Junction and Storage Temperature Range		-55 to 150	°C	

Thermal Characteristics

Symbol	Description	Тур	Max	Units	
$R_{\theta JA}$	Typical Junction-to-Ambient steady state 1	100	124	°C/W	
$R_{\theta JA2}$	Maximum Junction-to-Ambient t<5 seconds 1	62	76	°C/W	
$R_{\theta JF}$	Typical Junction-to-Foot ¹	35	42	°C/W	



Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Description	Conditions	Min	Тур	Max	Units
DC Charac	DC Characteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250μA	-20			V
	Drain-Source ON-Resistance ²	V _{GS} =-4.5V, I _D =-4.2A		45	57	mΩ
R _{DS(ON)}		V _{GS} =-2.5V, I _D =-3.1A		80	104	
I _{D(ON)}	On-State Drain Current ³	V_{GS} =-4.5V, V_{DS} =-5V (Pulsed)	-20			Α
V _{GS(th)}	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_{D}=-250\mu A$	-0.6			V
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±12V, V _{DS} =0V			±100	nA
	Drain Source Leakage Current	V_{GS} =0V, V_{DS} =-20V			-1	
I _{DSS}		V_{GS} =0V, V_{DS} =-16V, T_J =70°C ³			-5	μΑ
9 _{fs}	Forward Transconductance ²	V _{DS} =-5V, I _D =-4.2A		7		S
Dynamic C	Characteristics ³					•
Q_{G}	Total Gate Charge	V_{DS} =-10V, R_{D} =2.4 Ω , V_{GS} =-4.5V		8.5		
Q_{GS}	Gate-Source Charge	V_{DS} =-10V, R_{D} =2.4 Ω , V_{GS} =-4.5V		1.5		nC
Q_{GD}	Gate-Drain Charge	V_{DS} =-10V, R_{D} =2.4 Ω , V_{GS} =-4.5V		2.8		
t _{D(ON)}	Turn-ON Delay	V_{DS} =-10V, R_D =2.4 Ω , V_{GS} =-4.5V, R_G =6 Ω		10		
t_R	Turn-ON Rise Time	V_{DS} =-10V, R_D =2.4 Ω , V_{GS} =-4.5V, R_G =6 Ω		32		ns
t _{D(OFF)}	Turn-OFF Delay	V_{DS} =-10V, R_D =2.4 Ω , V_{GS} =-4.5V, R_G =6 Ω		61		115
t _F	Turn-OFF Fall Time	V_{DS} =-10V, R_D =2.4 Ω , V_{GS} =-4.5V, R_G =6 Ω		38		
Source-Dra	Source-Drain Diode Characteristics					
V _{SD}	Source-Drain Forward Voltage ²	V _{GS} =0, I _S =-4.2A			-1.3	V
Is	Continuous Diode Current 1				-1.2	Α

Notes:

^{1.} Based on thermal dissipation from junction to ambient while mounted on a 1" x 1" PCB with optimized layout. A 5 second pulse on a 1" x 1" PCB approximates testing a device mounted on a large multi-layer PCB as in most applications. R_{θJF} + R_{θFA} = R_{θJA} where the foot thermal reference is defined as the normal solder mounting surface of the device's leads. R_{θJF} is guaranteed by design, however R_{θCA} is determined by the PCB design. Actual maximum continuous current is limited by the application's design.

^{2.} Pulse test: Pulse Width = 300 μs

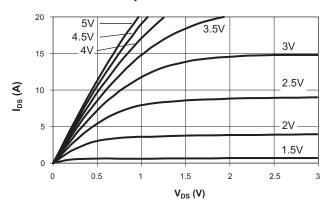
^{3.} Guaranteed by design. Not subject to production testing.



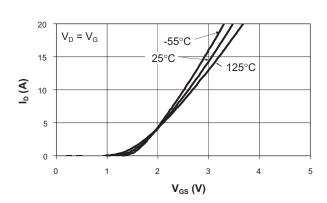
Typical Characteristics

(T_{.1} = 25°C unless otherwise noted)

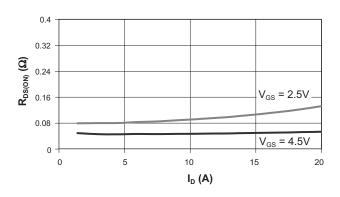
Output Characteristics



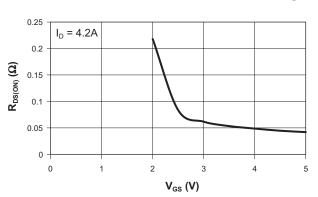
Transfer Characteristics



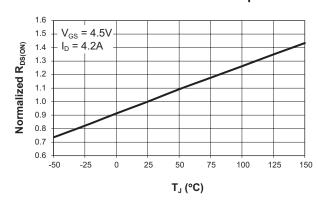
On-Resistance vs. Drain Current



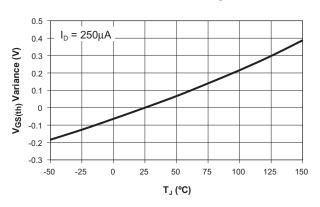
On-Resistance vs. Gate to Source Voltage



On-Resistance vs. Junction Temperature



Threshold Voltage

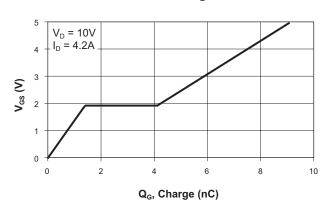




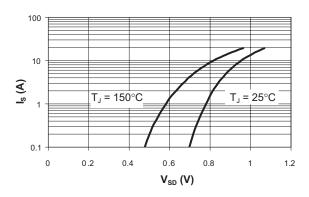
Typical Characteristics

(T_J = 25°C unless otherwise noted)

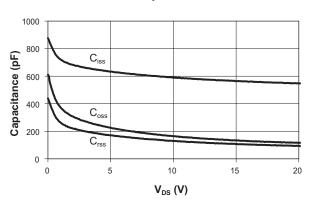
Gate Charge



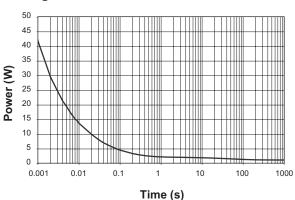
Source-Drain Diode Forward Voltage



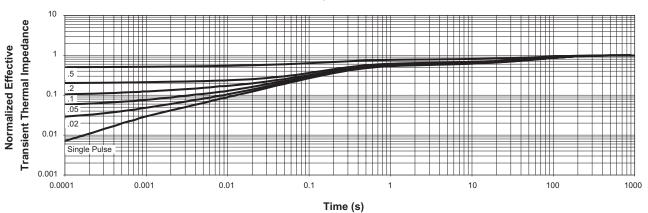
Capacitance



Single Pulse Power, Junction to Ambient



Transient Thermal Response, Junction to Ambient



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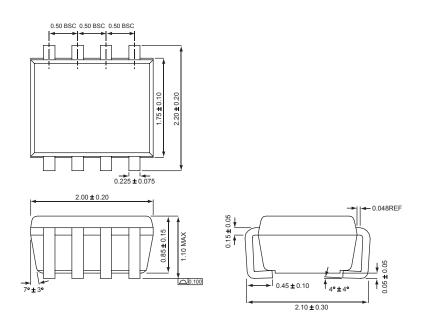
Ordering Information

Package	Marking¹	Part Number (Tape and Reel)
SC70JW-8	JTXYY	AAT8543IJS-T1

Note 1: XYY = assembly and date code.

Package Information

SC70JW-8



All dimensions in millimeters.



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